### Nch 60V 68A Power MOSFET

$V_{\mathrm{DSS}}$	60V
R <sub>DS(on)</sub> (Max.)	5.6mΩ
I <sub>D</sub>	±68A
P <sub>D</sub>	39W

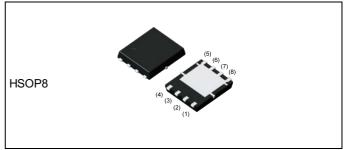
### Features

- 1) Low on resistance
- 2) High power package (HSOP8)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen free
- 5) 100% Rg and UIS tested
- 6) AEC-Q101 Qualified

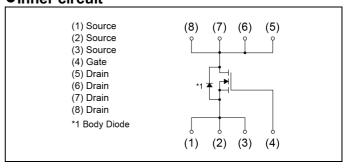
## Application

Switching

### Outline



### ●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	ТВ
	Marking	RS1L180GN

### ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V <sub>DSS</sub>	60	V	
Continuous dusin surmont	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±68	Α
Continuous drain current	T <sub>a</sub> = 25°C	I <sub>D</sub>	±18	Α
Pulsed drain current	I <sub>DP</sub> *2	±72	Α	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche current, single pulse	I <sub>AS</sub> *3	18	А	
Avalanche energy, single pulse		E <sub>AS</sub> *3	50	mJ
Davier dissination		P <sub>D</sub> *1	39	W
Power dissipation	P <sub>D</sub> *4	3.0	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage tem	perature range	T <sub>stg</sub>	-55 to +150	°C

### ●Thermal resistance

Doromotor	Cymah al	Values			I India
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	3.2	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	-	-	41.7	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymah ol	Conditions	Values			Unit	
Parameter	Symbol	ool Conditions -		Тур.	Max.	Urlit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	60	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	60	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	1	μА	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	1	1	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 100 \mu A$	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta  V_{GS(th)}}{\Delta  T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-5.6	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 18A	-	4.2	5.6	C	
on - state resistance	$R_{DS(on)}^{*5}$	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 18A	-	5.9	8.5	mΩ	
Gate resistance	R <sub>G</sub>	f=1MHz, open drain	-	1.5	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 5V, I <sub>D</sub> = 18A	25	-	-	S	

<sup>\*1</sup>T<sub>c</sub> =25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  0.2mH, V<sub>DD</sub> = 30V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Symbol Conditions			Unit			
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	3230	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 30V	-	630	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	160	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 30V, V_{GS} = 10V$	-	22	-		
Rise time	<b>t</b> <sub>r</sub> *5	I <sub>D</sub> = 9.0A	-	33	-		
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 3.3\Omega$	-	88	-	ns	
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	97	-		

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

Darameter	Cymahal	Conditions		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate above	O *5		V <sub>GS</sub> = 10V	-	63	-	
Total gate charge	$Q_g^{*5}$	$V_{DD} \simeq 30V$		-	34	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 18A	V <sub>GS</sub> = 4.5V	-	13.7	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5			-	12.2	-	

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Daramatar	Symbol Conditions			Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	2.5	Α
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	72	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_S = 2.5A$	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 18A, V <sub>GS</sub> =0V	-	41	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	51	-	nC

Fig.1 Power Dissipation Derating Curve

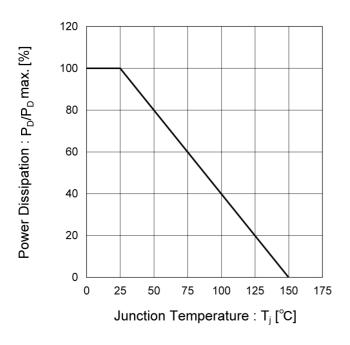
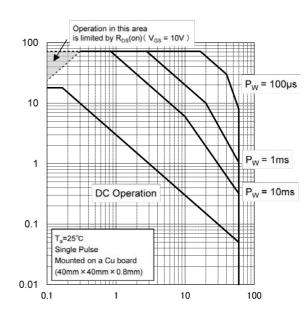


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

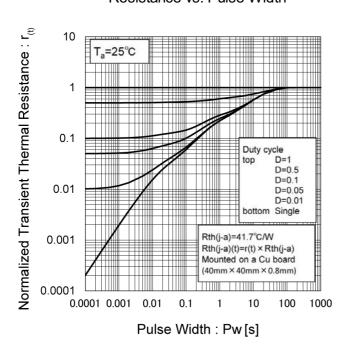
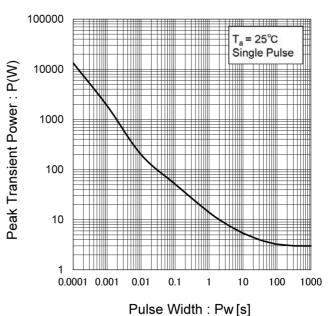


Fig.4 Single Pulse Maximum Power dissipation



Drain Current : I<sub>D</sub> [A]

### • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

18 17 V<sub>GS</sub>= 10V 16 V<sub>GS</sub>= 4.5V 15 V<sub>GS</sub>= 4.0V 14 V<sub>GS</sub>= 3.5V 13 12 11 10 T<sub>a</sub>=25°C 9 Pulsed 8 7 6 5 4 V<sub>GS</sub>= 3.0V 3 2 0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 0 Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)

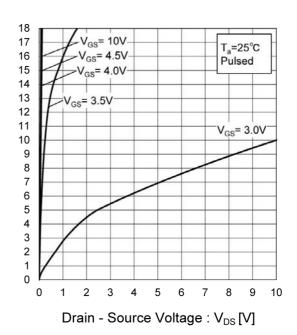


Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

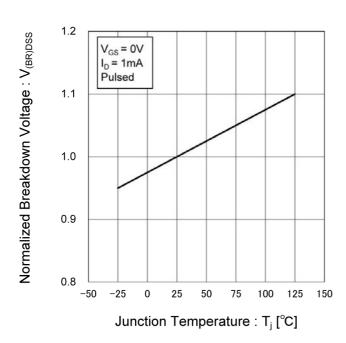
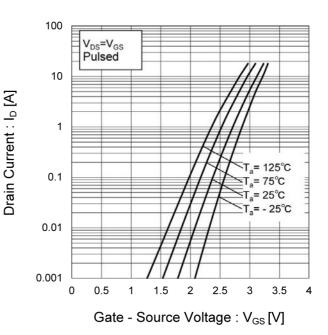


Fig.8 Typical Transfer Characteristics



Drain Current : I<sub>D</sub> [A]

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

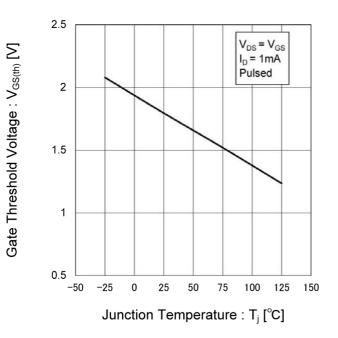


Fig.10 Forward Transfer Admittance vs.
Drain Current

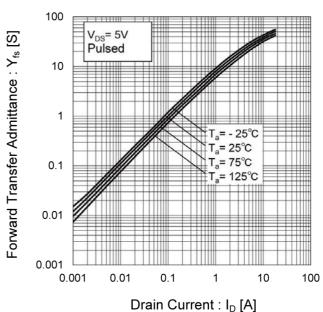


Fig.11 Drain Current Derating Curve

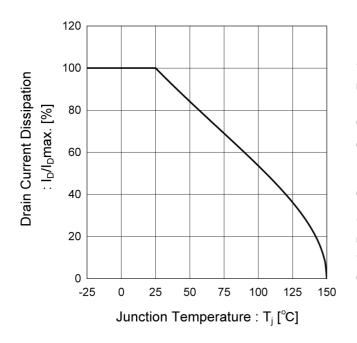


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

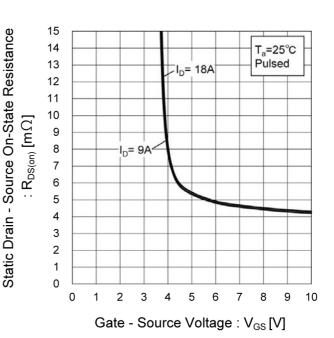


Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature

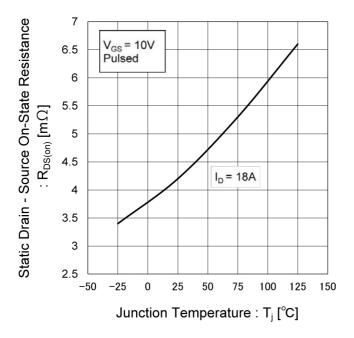


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

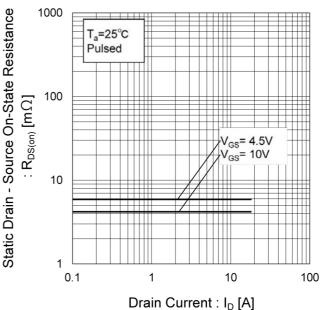


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

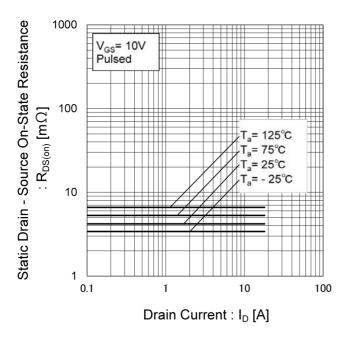


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

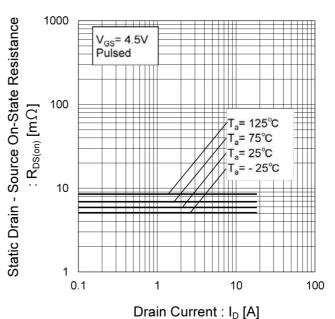


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

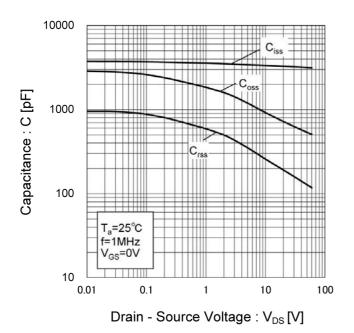


Fig.18 Switching Characteristics

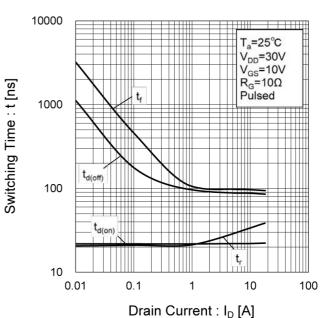


Fig.19 Dynamic Input Characteristics

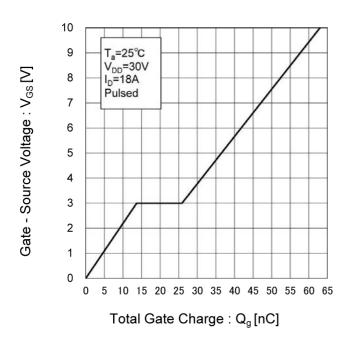
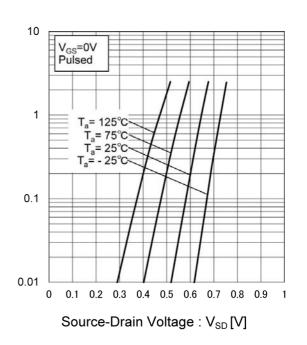


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

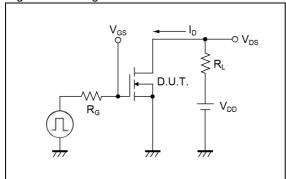


Fig.1-2 Switching Waveforms

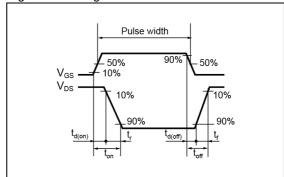


Fig.2-1 Gate Charge Measurement Circuit

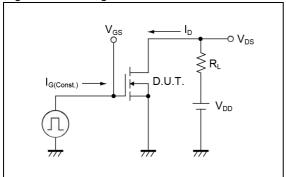


Fig.2-2 Gate Charge Waveform

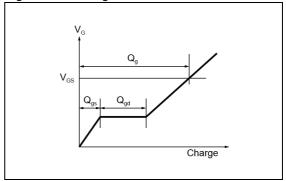


Fig.3-1 Avalanche Measurement Circuit

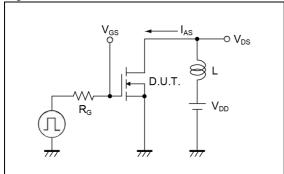
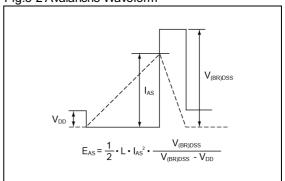


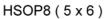
Fig.3-2 Avalanche Waveform

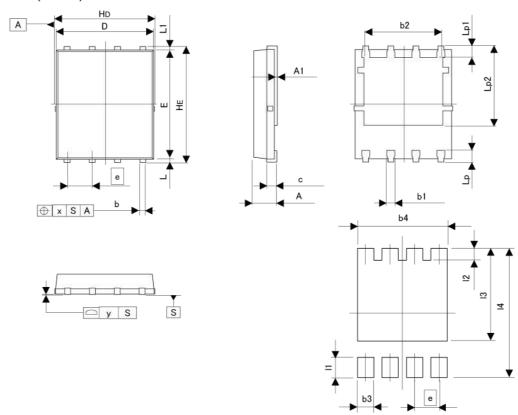


### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

### Dimensions





Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	0.90	1.10	0.035	0.043
A1	0.00	0.05	0.000	0.002
b	0.24	0.42	0.009	0.017
b1	0.29	0.49	0.011	0.019
b2	3.81	4.21	0.150	0.166
С	0.20	0.30	0.008	0.012
D	4.80	5.00	0.189	0.197
E	5.60	5.80	0.220	0.228
е	1.	27	0.0	)50
HD	4.90	5.10	0.193	0.201
HE	5.90	6.10	0.232	0.240
L	0.07	0.25	0.003	0.010
L1	0.07	0.25	0.003	0.010
Lp	0.50	0.70	0.020	0.028
Lp1	0.52	0.72	0.020	0.028
Lp2	3.92	4.32	0.154	0.170
х	- 0	0.10		0.004
У	-	0.10	-	0.004

DIM	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
b3	15	0.59	25	0.023
b4	¥	4.21	((4)	0.166
11	2	0.80	(2)	0.031
12		0.82	-	0.032
13	*	4.32	OH:	0.170
14		6.10		0.240

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГУООШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Notice-PGA-E Rev.004

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- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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